

Potting



In the potting process, a reservoir is filled with either a single-component or two-component resin to protect electronic components, connections or terminations. Resins may include epoxies, silicones and urethanes. Potting can be accomplished either at atmospheric pressure or under vacuum pressure when voids within the resin are undesirable, a process called vacuum encapsulation.

Typical products that might be potted include power supplies, sensors, switches, and control modules.

For single-component resins

[Graco 1052](#) - for shot sizes under 2.5 cc's

[Graco 1092](#) - for shot sizes under 14 cc's

[Graco 1095](#) - for shot sizes under 40 cc's

Graco single-component Posiload pumps - for shot sizes beyond 40 cc's

For two-component resins

[Graco PD44](#) - for shot sizes under 5 cc's.

[Graco PR70](#) - for shot sizes between 2 and 70 ccs's

[Graco HFR Metering System](#) - for shot sizes beyond 70 cc's

Feed systems (tanks) for all products mentioned can be configured as vacuum ready. Vacuum chambers can be integrated with any of the Graco products listed above by contacting Graco's Project Engineering group.